



General Description

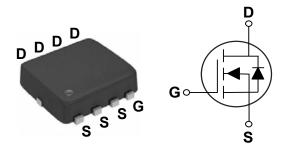
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
30V	3.8 mΩ	70 A

Features

- $R_{DS(ON)} \le 3.8 m\Omega @V_{GS} = 10V$
- · Improved dv/dt capability
- · Fast switching
- · Green Device Available

PPAK3X3 Pin Configuration



Applications

- Networking
- · Load Switch
- · LED applications
- · Hand-Held Device

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Parameter	Rating				
V_{DS}	Drain-Source Voltage	30	V			
V_{GS}	Gate-Source Voltage	±20	V			
1	Drain Current - Continuous (T _C =25°C)	70	Α			
I _D	Drain Current - Continuous (T _C =100°C)	50	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	128	Α			
P _D	Power Dissipation (T _C =25°C)	41	W			
T _J	Operating Junction Temperature Range	-50 to 150	°C			
T _{STG}	Storage Temperature Range	-50 to 150	°C			
Marking Code		NC3P8				

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	80	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	3	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30	-		V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25°C			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =9A			3.8	mΩ
		V_{GS} =4.5V , I_D =4A			6	11122
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0		2.5	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			55		
Q_{gs}	Gate-Source Charge	V_{DS} =15V , V_{GS} =10V , I_{D} =1.5A		14.7		nC
Q_{gd}	Gate-Drain Charge			31.9		
$T_{d(on)}$	Turn-On Delay Time			10.3		
T_r	Rise Time	V_{DS} =15V , V_{GS} =10V , R_{GEN} =3 Ω , I_{D} =1A		17.6		nS
$T_{d(off)}$	Turn-Off Delay Time			43.2		110
T_f	Fall Time			31.7		
C _{iss}	Input Capacitance			2435		
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , F=1MHz		308		pF
C_{rss}	Reverse Transfer Capacitance			259		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			70	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- ${\it 3. Essentially independent of operating temperature.}\\$





Characteristics Curves

Fig.1-Continuous Dr ain Current vs. T_C

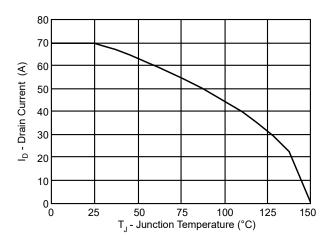


Fig. 2-Normalized R_{DSON} vs. T_J

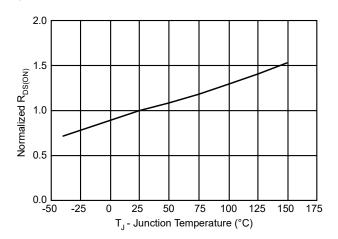


Fig. 3-Normalized $V_{GS(th)}$ vs. T_J

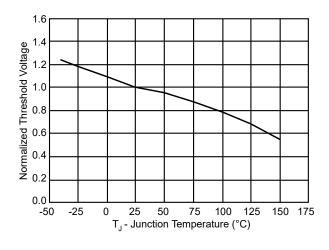


Fig. 4-Maximum Safe Operation Area

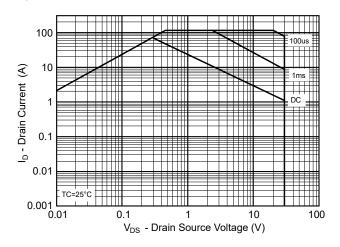


Fig. 5-R_{θJC} Transient Thermal Impedance

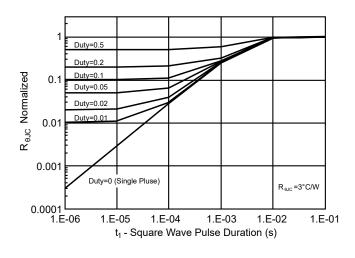
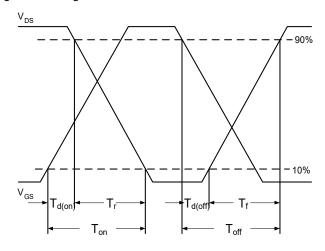


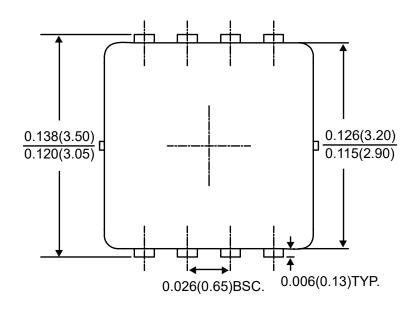
Fig. 6-Switching Time Waveform

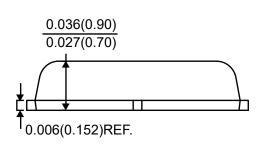


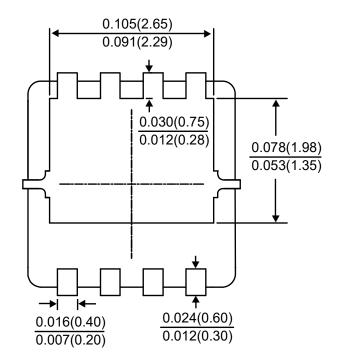


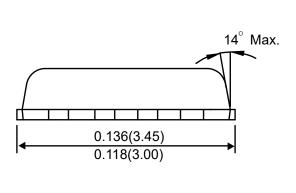


Package Outline Dimensions









PPAK3X3

Dimensions in inches and (millimeters)





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